

REMARKS

Applicants will address each of the Examiner's objections and rejections in the order in which they appear in the Final Rejection.

Drawings

In the Final Rejection, the Examiner objects to the drawings under 37 CFR 1.84(p)(5) as including reference numerals 317 and 334 in Fig. 11 but not in the specification. Accordingly, Applicants are amending page 30 of the specification to add reference numerals 317 and 334. As these reference numerals were in the drawings as filed, no new matter is being added. Therefore, it is respectfully requested that this amendment be entered, and the objection withdrawn.

Claim Rejections - 35 USC §112

The Examiner also rejects Claims 42-77 under 35 USC §112, second paragraph, as being indefinite. This rejection is respectfully traversed.

In particular, the Examiner objects to the phrase "organic EL layer" as lacking an antecedent basis in Claims 42, 47, 52, 57, 62 and 67. Accordingly, Applicants are amending each of these claims as follows: "organic EL layer." As there is a clear antecedent basis for "EL layer", it is respectfully submitted that this rejection has been overcome, and it is requested that the rejection be withdrawn.

Claim Rejections - 35 USC §103

Claims 42-45, 47-49, 51 and 72-73

The Examiner also rejects Claims 42-45, 47-49, 51 and 72-73 under 35 U.S.C §103(a) as being unpatentable over Kimura et al. (US6,518,962) in view of Shields (US 4,839,707) and Yasukawa (US6,831,623). This rejection is respectfully traversed.

With respect to independent Claims 42 and 47, the Examiner contends that Kimura discloses all the limitations of these claims except for an insulating layer formed on the semiconductor substrate and a power supply line formed on the dielectric layer. The Examiner then cites Shields as allegedly disclosing a SOI structure and Yasukawa for allegedly disclosing a power supply line formed on the dielectric layer, and contends that these references allegedly cure the deficiencies in Kimura. Applicants respectfully disagree.

More specifically, the present application discloses in Fig. 11, an electrode 323 formed over an interlayer insulating film 322, a dielectric layer 324 formed on the electrode 323, and a power supply line 19a formed on the dielectric layer 324. Independent Claims 42 and 47 claim such a structure.

In contrast, the Examiner cites to Fig. 20 in Kimura which appears to disclose an electrode 132 formed over an interlayer insulating film 252 and a dielectric layer 253 formed on the electrode 132. As the Examiner admits, Kimura fails to disclose a power supply line formed on the dielectric layer 253. Therefore, the Examiner cites Yasukawa.

Yasukawa appears to disclose in cited Fig. 2, an electrode 27a formed over an interlayer insulating film 6, and a dielectric layer 11 formed on the electrode 27a. Yasukawa does *not* appear to disclose or suggest a power supply line formed on the dielectric layer 11. In the Final Rejection,

the Examiner states that Yasukawa discloses “a power supply line...formed on the dielectric layer 6” (page 5, last 4 lines in office action; emphasis added). Layer 6, however, is not the dielectric layer but is instead the interlayer insulating layer. While the Examiner does not identify the alleged power supply line, it appears that the Examiner is alleging that Yasukawa discloses a power supply line 27b formed on the interlayer insulating film 6. Yasukawa does not disclose alleged power supply line 27b formed on the dielectric layer 11 (as required in the claims). Hence, Yasukawa fails to disclose or suggest the claimed feature of “a power supply line.. formed on the dielectric layer”, and there has been no showing by the Examiner of this feature.

Therefore, since this claimed feature is also not disclosed or suggested by the other references, independent Claims 42 and 47 and those claims dependent thereon are patentable over the cited references. Accordingly, it is respectfully requested that this rejection be withdrawn.

Claims 52-54, 57-59, 61-69, 71 and 74-77

The Examiner also rejects Claims 52-54, 57-59, 61-69, 71 and 74-77 under 35 USC §103(a) as being unpatentable over Kimura et al. in view of Yasukawa. This rejection is also respectfully traversed.

For substantially the same reasons as discussed above, the cited references also do not disclose or suggest the claimed feature of a power supply line formed on the dielectric layer, in the claimed structure, of independent Claims 52, 57, 62 and 67. Therefore, independent Claims 52, 57, 62 and 67 and those claims dependent thereon are patentable over the cited references. Accordingly, it is respectfully requested that this rejection be withdrawn.

Claims 46 and 50

The Examiner also rejects Claims 46 and 50 under 35 USC §103(a) as being unpatentable over Kimura et al., Shields and Yasukawa and further in view of Ue et al. (US 5,733,661). This rejection is also respectfully traversed.

Each of these claims is a dependent claim. Therefore, for at least the reasons discussed above for the independent claims, these claims are also patentable over the cited references. Accordingly, it is respectfully requested that this rejection be withdrawn.

Claims 55, 60, 65 and 71

The Examiner also rejects Claims 55, 60, 65 and 71 under 35 USC §103(a) as being unpatentable over Kimura et al., Yasukawa and further in view of Ue et al. This rejection is also respectfully traversed.

Each of these claims is a dependent claim. Therefore, for at least the reasons discussed above for the independent claims, these claims are also patentable over the cited references. Accordingly, it is respectfully requested that this rejection be withdrawn.

Conclusion

It is respectfully submitted that the present application is in a condition for allowance and should be allowed.

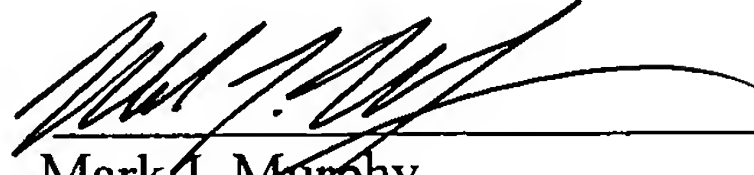
If any fee is due for this amendment, please charge our deposition account 50/1039.

Favorable reconsideration is earnestly solicited.

Respectfully submitted,

Dated:

June 8, 2006


Mark J. Murphy
Registration No. 34,225

COOK, ALEX, McFARRON, MANZO,
CUMMINGS & MEHLER, Ltd.
200 West Adams Street, Suite 2850
Chicago, Illinois 60606
(312) 236-8500

Customer no. 26568